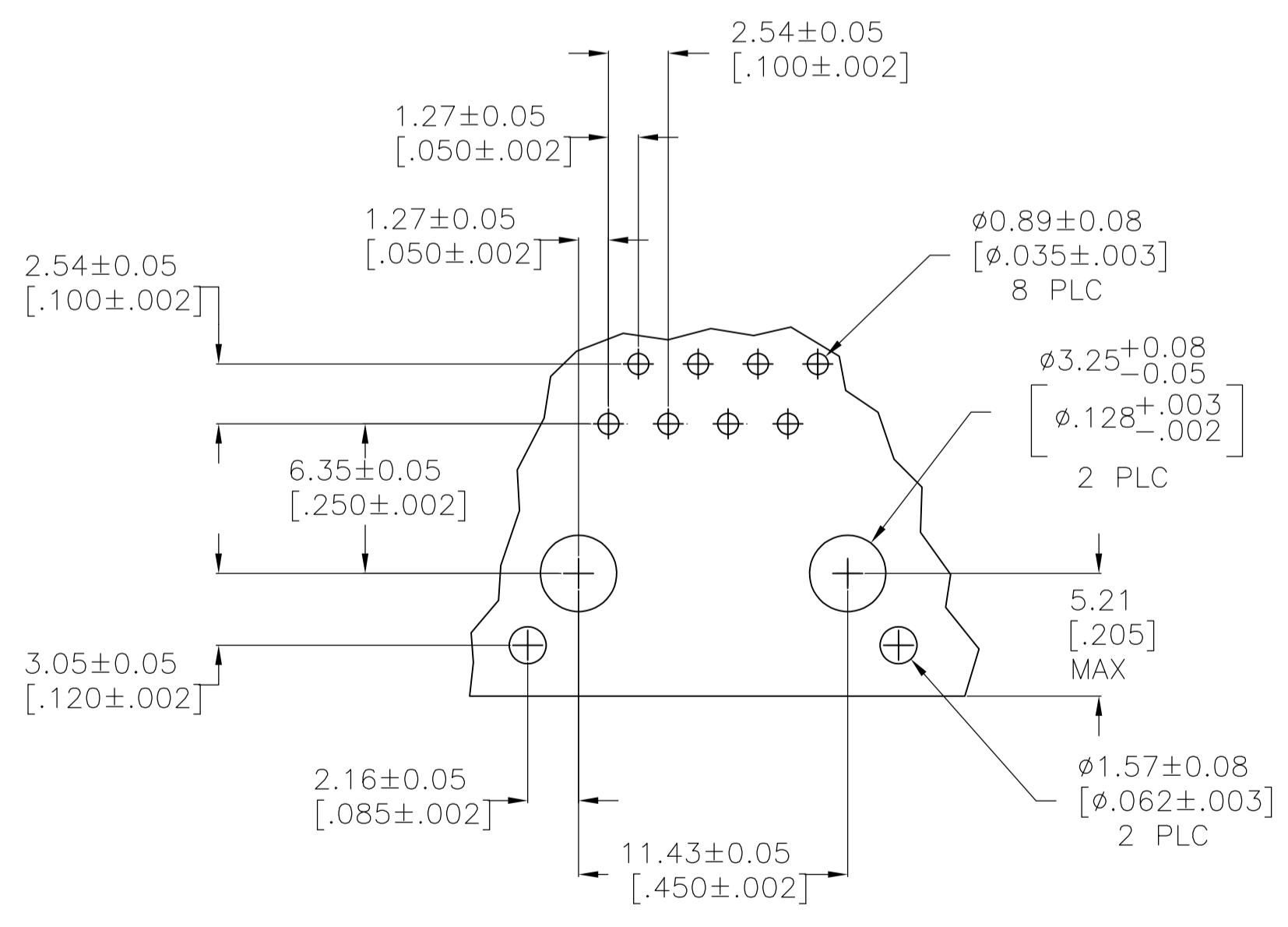
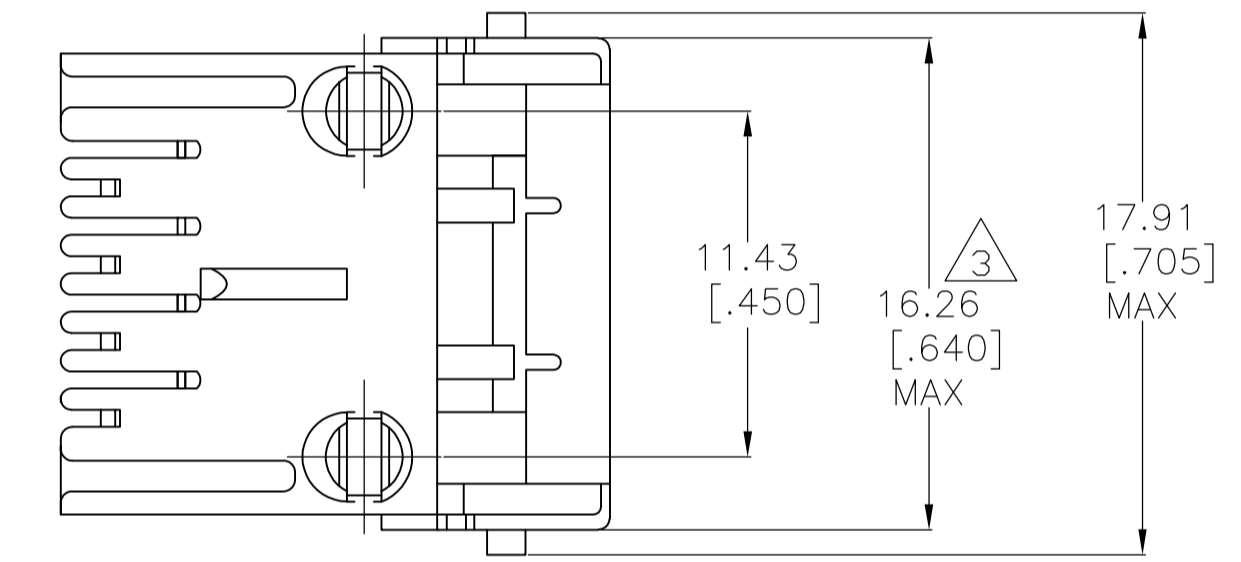
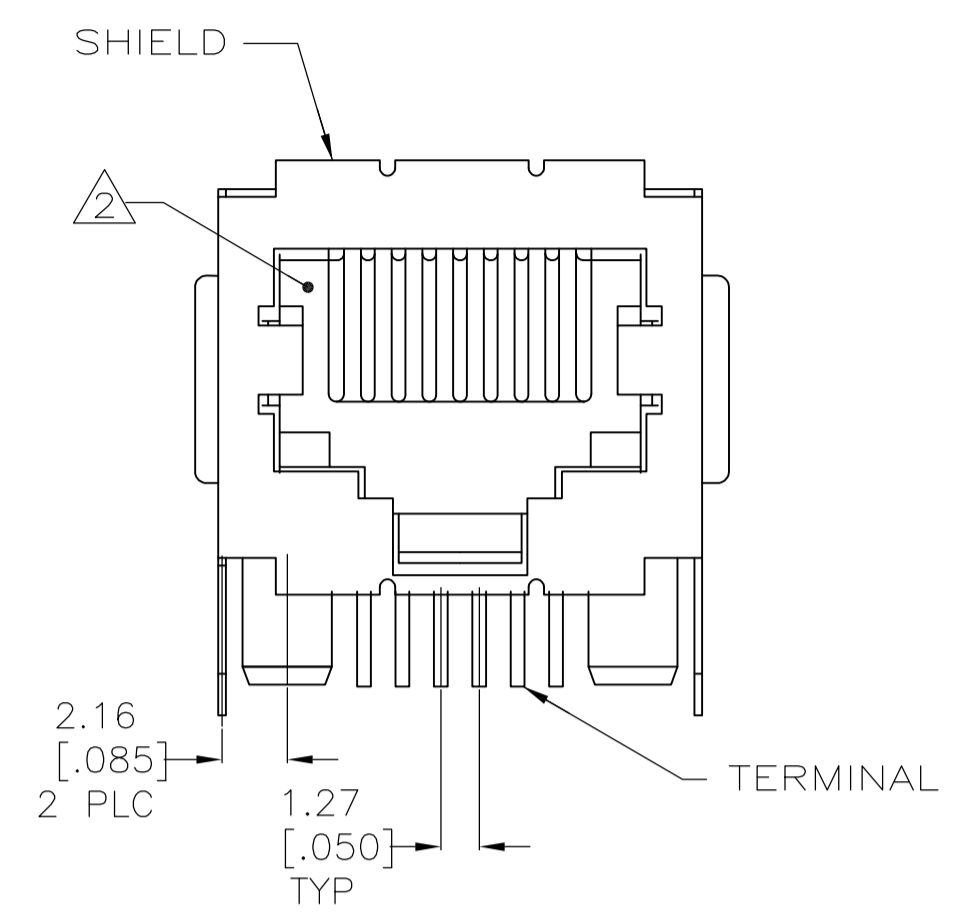
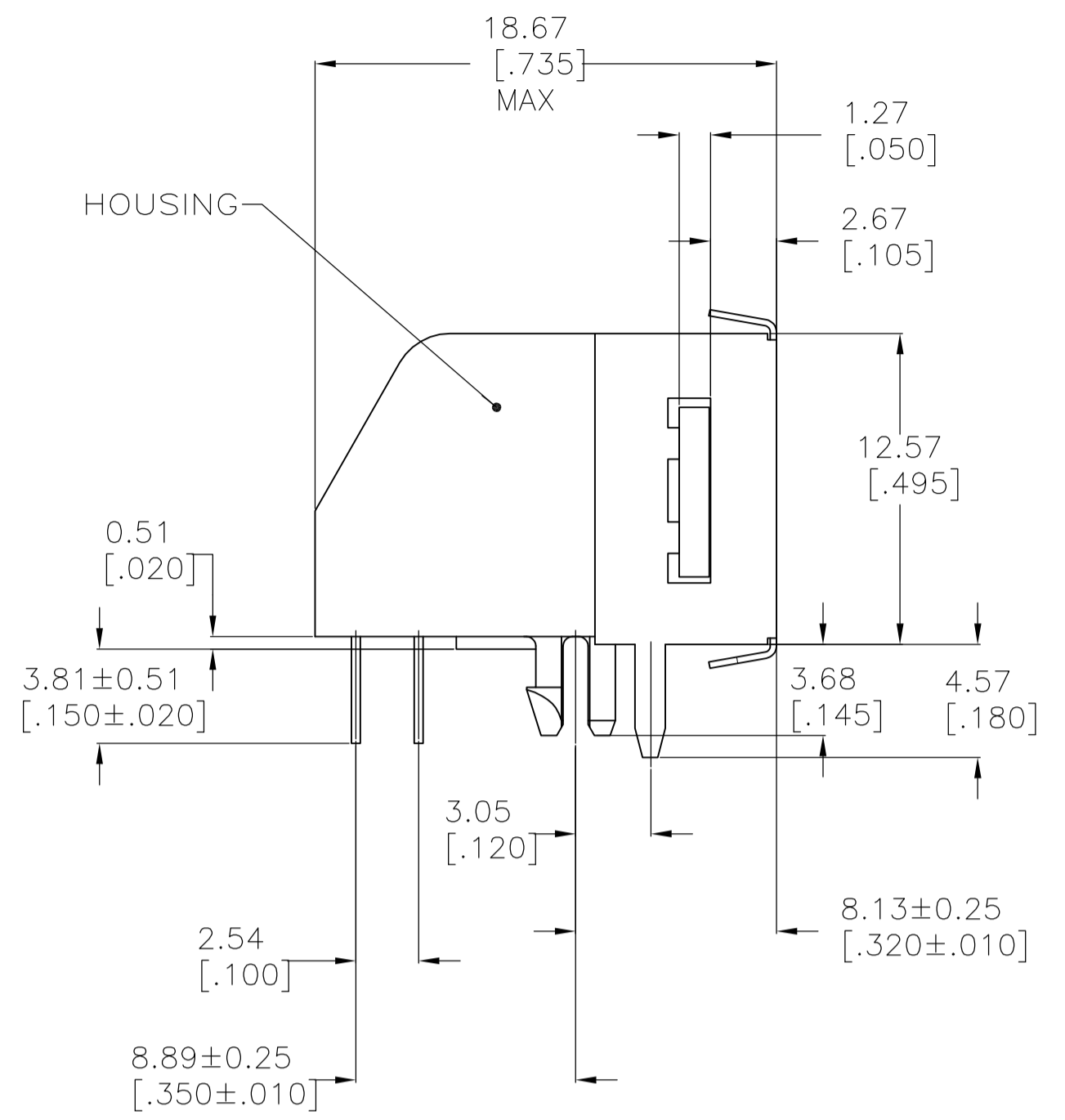
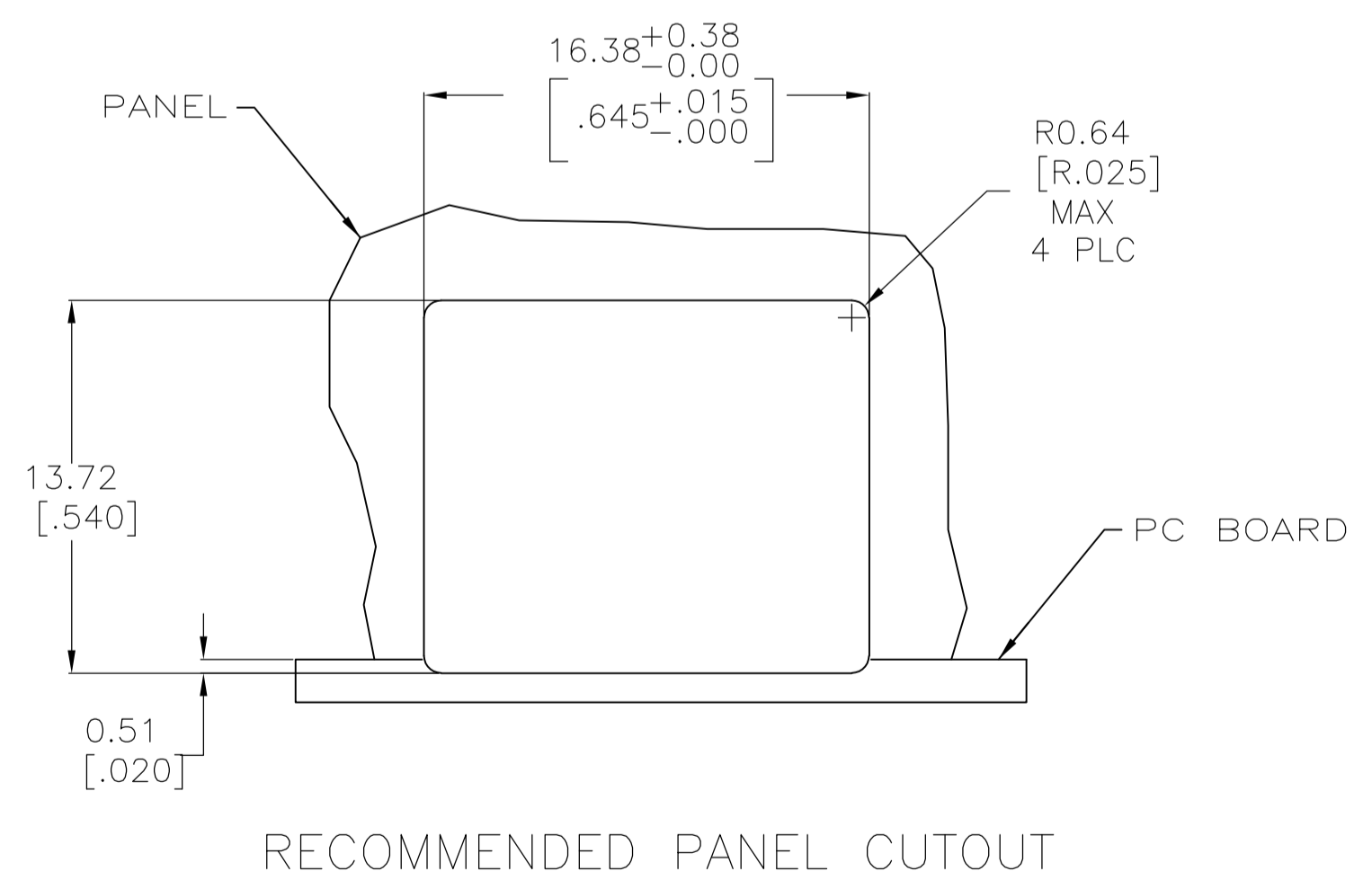


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
B	ECO-07-026026		05NOV07	LAM	PR		



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

1. MATERIAL:  
 HOUSING (SEE TABLE) - COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE  
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0µm [.000120] MINIMUM THICK REFLOWED TIN
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. GARRETT/L.A. MAYER 04APR2005		Tyco Electronics Corporation Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 04APR2005	
0 PLC ± -		1 PLC ± -		NAME MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS	
1 PLC ± -		2 PLC ± 0.13[.005]		PRODUCT SPEC 108-1163	
2 PLC ± -		3 PLC ± -		APPLICATION SPEC 114-2048	
3 PLC ± -		4 PLC ± -		SIZE CAGE CODE DRAWING NO RESTRICTED TO A1 00779 C=5555141	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT -	
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 OF 1 REV B	